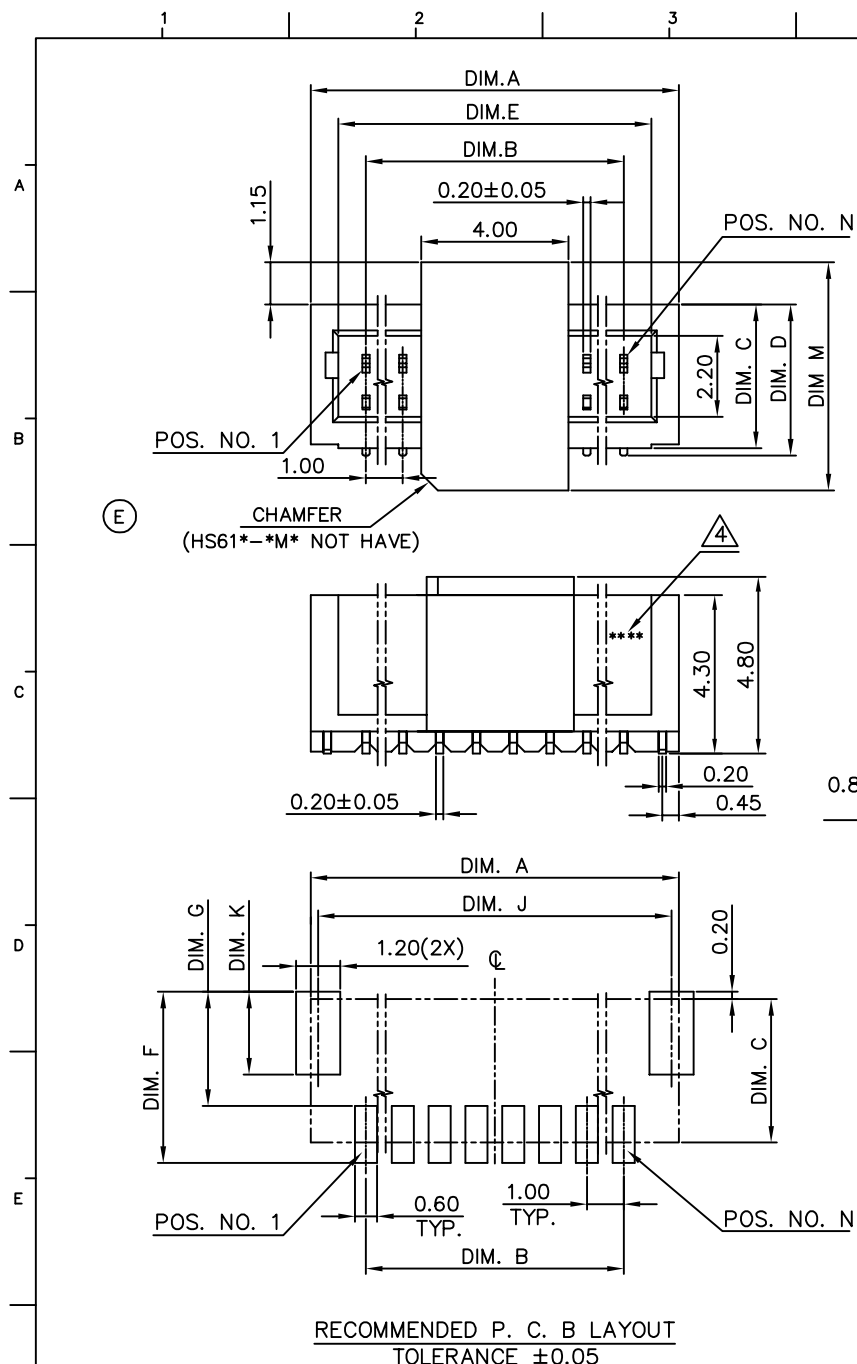
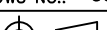




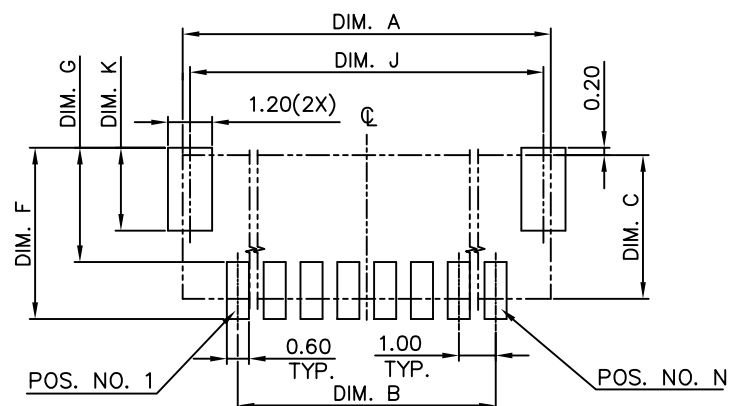
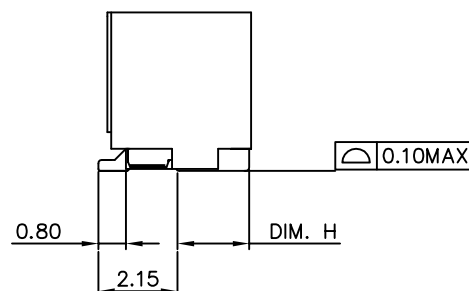
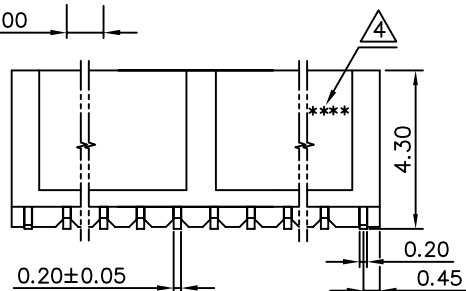
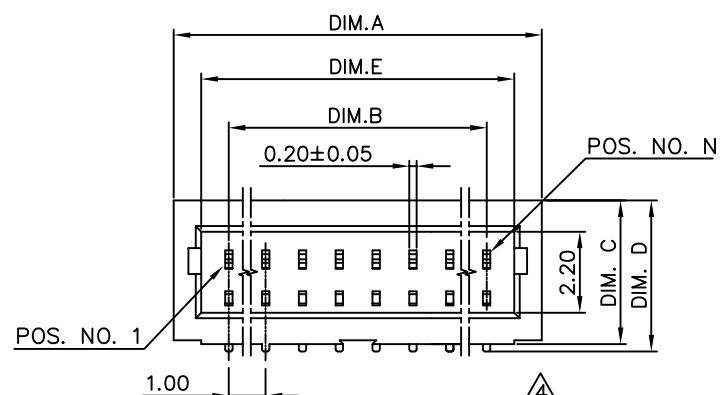
REV.	ECN. NO.	APPD.
A	BC0351020	Yihsin Chen
B	BC-06-741336	Yusan
C	BC-06-779647	Yusan
D	BC-17-0025307	Shih-Wei Hsiao
E	BC-20-0014250	Shih-Wei Hsiao

NOTES: (UNLESS OTHERWISE SPECIFIED)

- DIMENSIONS SHALL BE INTERPRETED PER ASME Y14.5-2009.
- SPEC. OF PROD. ARE SHOWN ON DRAWING "307-0100-266".
- MATERIALS OF PARTS ARE SHOWN ON DRAWING "307-0100-264".
- DATE CODE: PLEASE REFER TO FOXCONN'S DOC. "SQ-3B0-070" WHEN POS. No. IS 8 OR MORE.
- PRODUCT NO. MATRIX: PLEASE REFER TO DRAWING "307-0100-264".
- HARMFUL MATERIAL CONTROL PLEASE FOLLOW FOXCONN'S DOC. "EPI12".
- PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAIL & AVAILABILITY.
- POCKET SHAPE OF PACKAGE ONLY FOR REFERENCE

X.±	X.± 3*	UNITS mm	NAME(INTENDED USE) HEADER CONN. SINGLE ROW,VERTICAL,SMT	 FOXCONN INTERCONNECT TECHNOLOGY LIMITED.								
.X± 0.10	.X*±	MAT'L	PART NO.(INTENDED USE) HS61 SERIES	CLASS: ☐ CONFIDENTIAL ☐ SECRET ☒ GENERAL								
.XX±0.05	.XX*±											
.XXX±	.XXX*±	FINISH	APPD: Shih-Wei Hsiao	TITLE: CUSTOMER DRAWING								
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED,AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.		Q'TY	CHKD: Tony Chen	DWG NO.: 307-0100-265								
			DRAW: Vemin Wu 7/2 2020	 <table><tr><th>SCALE</th><th>SHEET</th><th>REV.</th></tr><tr><td>1:1</td><td>1/3</td><td>E</td></tr></table>			SCALE	SHEET	REV.	1:1	1/3	E
			SCALE	SHEET	REV.							
1:1	1/3	E										

PROD. NO. HS61***-*



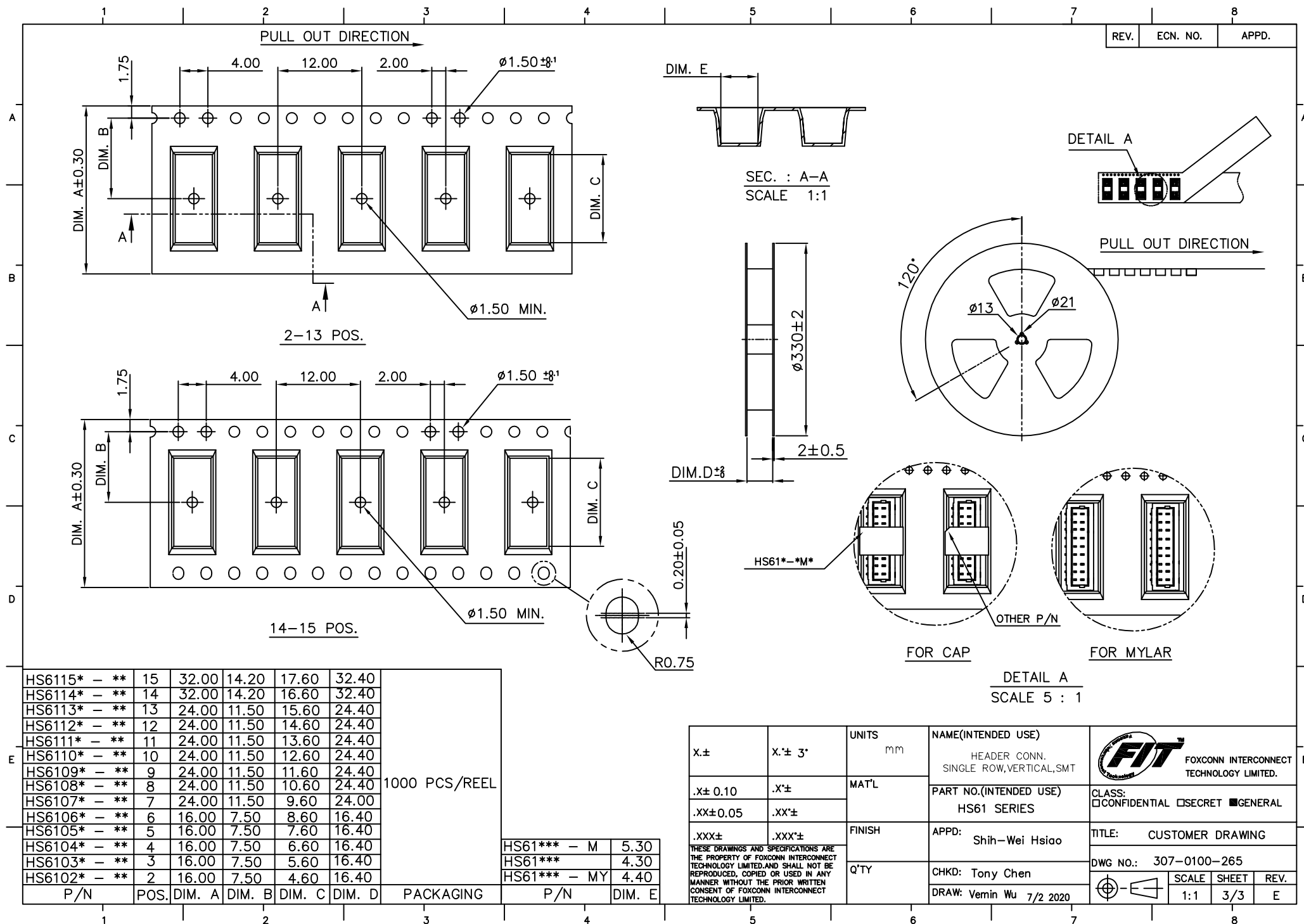
RECOMMENDED P. C. B LAYOUT
TOLERANCE ± 0.10

PROD. NO. HS61***-Y

HS6115* - **	17.3	14.00	15.50	16.60
HS6114* - **	16.3	13.00	14.50	15.60
HS6113* - **	15.3	12.00	13.50	14.60
HS6112* - **	14.3	11.00	12.50	13.60
HS6111* - **	13.3	10.00	11.50	12.60
HS6110* - **	12.3	9.00	10.50	11.60
HS6109* - **	11.3	8.00	9.50	10.60

DIM. P/N	HS61*** - *M*	HS61***-*	HS6108* - **	10.3	7.00	8.50	9.60
DIM.C	3.90	2.90	HS6107* - **	9.3	6.00	7.50	8.60
DIM.D	4.10	3.60	HS6106* - **	8.3	5.00	6.50	7.60
DIM.F	4.65	4.20	HS6105* - **	7.3	4.00	5.50	6.60
DIM.G	3.10	2.65	HS6104* - **	6.3	3.00	4.50	5.60
DIM.H	1.95	1.50	HS6103* - **	5.3	2.00	3.50	4.60
DIM.K	2.25	1.80	HS6102* - **	4.3	1.00	2.50	3.60
DIM.M	6.20	5.20	PROD. NO.	DIM.A	DIM.B	DIM.E	DIM.J

X $\pm$	X $\pm$ 3°	UNITS mm	NAME(INTENDED USE) HEADER CONN. SINGLE ROW, VERTICAL, SMT	 FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X $\pm$ 0.10	.X $\pm$	MAT'L	PART NO.(INTENDED USE) HS61 SERIES	
.XX $\pm$ 0.05	.XX $\pm$	FINISH	APPD: Shih-Wei Hsiao	CLASS: ☐ CONFIDENTIAL ☐ SECRET ☒ GENERAL
.XXX $\pm$	.XXX $\pm$	Q'TY	CHKD: Tony Chen	TITLE: CUSTOMER DRAWING
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.		DRAW: Vemin Wu 7/2 2020	DWG NO.: 307-0100-265	SCALE SHEET REV. 1:1 2/3 E



REV.	ECN. NO.	APPD.
A	BC06746292	Yusan
B	BC077061630	Yihsin Chen

SPECIFICATIONS :

1. PHYSICAL :

1-1. HOUSING :

LCP , THERMOPLASTIC , UL94V-0 FOR HS61***-**LH;
PA9T , THERMOPLASTIC , UL94V-0 FOR OTHERS.

1-2. CONTACT :

PHOSPHOR BRONZE , 50u" MIN. NICKEL UNDER PLATING OVER ALL ,
100u" MIN. MATTED TIN OR GOLD PLATING OVER NICKEL WITH RoHS COMPLIANCE.

1-3. PAD :

PHOSPHOR BRONZE , 50u" MIN. NICKEL UNDER PLATING OVER ALL , 100u"
MIN. MATED TIN PLATING OVER NICKEL WITH RoHS COMPLIANCE.

1-4. PICK UP CAP:

HIGH TEMPERATURE , THERMOPLASTIC , UL94V-0 , COLOR BLACK.

2. ELECTRICAL CHARACTERISTICS :

2-1. CURRENT RATING : 1.5 A MAX. PER CONTACT.

2-2. LOW LEVEL CONTACT RESISTANCE : 30 MILLIOHMS MAX. INITIAL.

2-3. DIELECTRIC WITHSTANDING VOLTAGE : 250V AC FOR 1 MINUTE.

2-4. INSULATION RESISTANCE : 1000 MEGOHMS MIN.

3. MECHANICAL CHARACTERISTICS :

3-1. RETENTION FORCE: 0.35Kgf MIN. PER POS..

3-2. MATING & UNMATING FORCE IS AS BELLOW:(UNIT: N)

PRODUCT No.:	AT INITIAL		AT 30TH
	I.F.(MAX.)	W.F.(MIN.)	W.F.(MIN.)
HS6102/03/04*-***	20	2	2
HS6105/06/07*-***	30	3	3
HS6108/09/10*-***	40	4	4
HS6111/12/13*-***	50	5	5
HS6114/15*-***	60	6	6

4. ENVIRONMENTAL DATA:

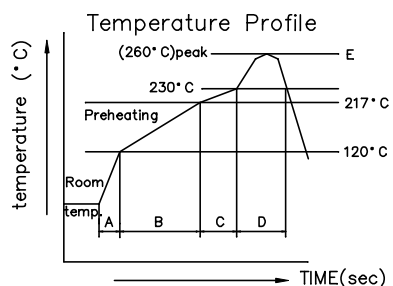
4-1. OPERATING TEMPERATURE : -25°C TO +85°C.

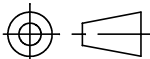
4-2. SOLDERABILITY : PASSED EIA-364-52.

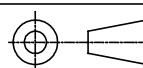
4-3. HARMFUL MATERIAL CONTROL PLEASE FOLLOW FOXCONN'S DOC. "EPI12"

5. PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.

6. INFRARED REFLOW PROFILE CONDITION:



X. ±	X.* ±	UNITS mm	NAME(INTENDED USE)	 FOXCONN INTERCONNECT TECHNOLOGY LIMITED.									
.X±	.X* ±	MAT'L	SINGLE ROW, VERTICAL, SMT	CLASS: ☐ CONFIDENTIAL ☐ SECRET ☒ GENERAL									
.XX±	.XX* ±		PART NO.(INTENDED USE) HS61 SERIES	TITLE: SPECIFICATION									
.XXX±	.XXX* ±	FINISH	APPD: Shih—Wei Hsiao	DWG NO.: 307—0100—266									
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED. AND SHALL NOTBE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.		Q'TY	CHKD: Tony Chen	<table><tr><td>SCALE</td><td>SHEET</td><td>REV.</td></tr><tr><td>N/A</td><td>1/1</td><td>BX3</td></tr></table>				SCALE	SHEET	REV.	N/A	1/1	BX3
			SCALE					SHEET	REV.				
N/A	1/1	BX3											
		DRAW: Vemin Wu 3/21 2019											

1			2			3			4						
NOTES : 1. HARMFUL MATERIAL CONTROL PLEASE FOLLOW FOXCONN'S DOC. "EPI12". 2. PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY. 3. THE CONCENTRATIONS OF Br&Cl CAN SATISFY THE REQUIREMENT OF HALOGEN-FREE IN DOCUMENT "EPI12". 4. PRODUCT NO. MATRIX: H S 61 ** * - * * * * ** NO. OF POS. _____ 02 = 02 POS. 03 = 03 POS. ⋮ PLATING CODE _____ E = TIN PLATING H = 30u" GOLD V = 15u" GOLD F = 1u" GOLD HOUSING COLOR _____ NONE =WHITE OR IVORY B = BLACK NONE =PA9T&RoHS PRODUCT LH= LCP&HALOGEN FREE NONE = CAP WITH TAPE&REEL Y = MYLAR WITH TAPE&REEL NONE= WITH "H" OR "FOXCONN" Q= WITHOUT "H" OR "FOXCONN" NONE=STANDARD TYPE M= STRENGTH TYPE						REV.	ECN NO.		APPD.						
						A	BC06746239		Yusan 8/4'06						
						B	BC-07-7061624		Yusan 9/25'07						
						C	BC-08-7152075		Jake W.Y						
4						PICK UP CAP		1	LCP, THERMOPLASTIC, UL 94V-0		COLOR BLACK				
3						SOLDER PAD		2	PHOSPHOR BRONZE		A) 50u" MIN. NICKEL UNDER PLATING OVER ALL B) 100u" MIN. MATTE TIN OVER NICKEL WITH RoHS COMPLIANCE				
2						CONTACT		SEE NOTE ABOVE	PHOSPHOR BRONZE		A) 50u" MIN. NICKEL UNDER PLATING OVER ALL B) 100u" MIN. MATTE TIN OR GOLD PLATING OVER NICKEL WITH RoHS COMPLIANCE				
1						HOUSING		1	HIGH TEMP. PA9T OR LCP UL 94V-0		COLOR IVORY OR BLACK				
ITEM						DESC.		Q'TY	MATERIAL		TREATMENT		REMARK		
X.±						X.° ±		UNITS mm	NAME(INTENDED USE)		FOXCONN®		FOXCONN INTERCONNECT TECHNOLOGY LIMITED.		
.X±						.X° ±		MAT'L	SINGLE ROW, VERTICAL, SMT		CLASS: □CONFIDENTIAL □SECRET ■GENERAL				
.XX±						.XX° ±			PART NO.(INTENDED USE)		TITLE: MATERIAL SHEET				
.XXX±						.XXX° ±		FINISH	HS61 SERIES		DWG NO.: 307-0100-264				
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED. AND SHALL NOTBE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.						Q'TY		CHKD: Tony Chen	APPD: Shih-Wei Hsiao				SCALE N/A	SHEET 1/1	REV. CX1
									DRAW: Vemin Wu 3/26 2019						
1			2			3			4						